

K.Y. Hwang  
USSN 09/982,493  
Page 2

**Amendments To The Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

1. (Presently amended) An amino resin composition for cleaning molds, comprising 30 to 60 wt. % of thermosetting resin ~~which consists of~~ and 40 to 70 wt. % of at least one methanol-containing amino resin having at least 75 wt. % of solid content.
2. (Previously amended) The amino resin composition for cleaning molds according to claim 1, wherein said amino resin is selected from the group consisting of urea, amino compounds of melamine, formaldehyde and the derivatives thereof.
3. (Original) The amino resin composition for cleaning molds according to claim 1, further comprising xylon material, inorganic filling material, a releasing agent, and a hardening promoter.
4. (Original) The amino resin composition for cleaning molds according to claim 3, wherein said inorganic filling material is selected from the group consisting of metal oxides, metal hydroxides, metal carbonates, metal sulfates, metal sulfides, metal silicates, metal silicides, mineral powders, and glass fibers and the added amount is from 0.01 to 80 wt. %, based on the weight of the amino resin composition.
5. (Original) The amino resin composition for cleaning molds according to claim 3, wherein said inorganic filling material is mineral powder which has a mean particle size less than 150  $\mu\text{m}$ .
6. (Original) The amino resin composition for cleaning molds according to claim 3, wherein said releasing agent is selected from the group consisting of aliphatic releasing agent, aliphatic amido releasing agent, alcoholic releasing agent, paraffinic releasing

K.Y. Hwang  
USSN 09/982,493  
Page 3

- agent and silicic releasing agent and the added amount is from 0.01 wt. % to 10 wt. % based on the total weight of the amino resin composition.
7. (Original) The amino resin composition for cleaning molds according to claim 6, wherein the added amount of said releasing agent is preferably from 0.5 wt % to 5.0 wt %, based on the total weight of the amino resin composition.
  8. (Original) The amino resin composition for cleaning molds according to claim 3, wherein said hardening promoter is selected from the group consisting of inorganic acidic hardening promoter, organic acidic hardening promoter, organic ammonium salt hardening promoter and inorganic metal salt hardening promoter and the added amount is from 0.01 to 10 wt. %, based on the weight of the amino resin composition.
  9. (Original) The amino resin composition for cleaning molds according to claim 3, wherein said xylon fiber material contains at least 80 wt. % of particles which can pass through sieve No. 80 and the added amount is within the range of from 10 wt. % to 80 wt. %, based on the total weight of the amino resin composition.
  10. (Previously amended) The amino resin composition for cleaning molds according to claim 1, wherein curing time of the amino resin composition for cleaning molds is in the range of 450 to 750 seconds, measured by using JSR type of curing meter.
  11. (Previously amended) The amino resin composition for cleaning molds according to claim 1, which is made into a tablet form.
  12. (Previously amended) The amino resin composition for cleaning molds according to claim 1, which is made into a sheet form.
  13. (Previously amended) The amino resin composition for cleaning molds according to claim 1, which is made into a powder form.
  14. (Presently amended) An amino resin composition for cleaning molds, comprising 30 to 60 wt. % of thermosetting resin ~~which consists of~~ and 40 to 70 wt. % of a semi-cured

K.Y. Hwang  
USSN 09/982,493  
Page 4

additive of at least one methylol-containing amino resin having at least 75 wt. % of solid content.

15. (Previously amended) The amino resin composition for cleaning molds according to claim 14, wherein said amino resin is selected from the group consisting of urea, amino compounds of melamine, formaldehyde and the derivatives thereof.
16. (Original) The amino resin composition for cleaning molds according to claim 14, further comprising xylon material, inorganic filling material, a releasing agent, and a hardening promoter.
17. (Original) The amino resin composition for cleaning molds according to claim 16, wherein said inorganic filling material is selected from the group consisting of metal oxides, metal hydroxides, metal carbonates, metal sulfates, metal sulfides, metal silicates, metal silicides, mineral powders, and glass fibers and the added amount is from 0.0 t to 80 wt. %, based on the weight of the amino resin composition.
18. (Original) The amino resin composition for cleaning molds according to claim 16, wherein said inorganic filling material is mineral powder which has a mean particle size less than 150  $\mu\text{m}$ .
19. (Original) The amino resin composition for cleaning molds according to claim 16, wherein said releasing agent is selected from the group consisting of aliphatic releasing agent, aliphatic amido releasing agent, alcoholic releasing agent, paraffinic releasing agent and silicic releasing agent and the added amount is from 0.01 wt. % to 10 wt %, based on the total weight of the amino resin composition.
20. (Original) The amino resin composition for cleaning molds according to claim 19, wherein the added amount of said releasing agent is preferably from 0.5 wt. % to 5.0 wt %, based on the total weight of the amino resin composition.
21. (Original) The amino resin composition for cleaning molds according to claim 16, wherein said hardening promoter is selected from the group consisting of inorganic acidic hardening promoter, organic acidic hardening promoter, organic ammonium salt

K.Y. Hwang  
USSN 09/982,493  
Page 5

hardening promoter and inorganic metal salt hardening promoter and the added amount is from 0.01 to 10 wt. %, based on the weight of the amino resin composition.

22. (Original) The amino resin composition for cleaning molds according to claim 16, wherein said xylon fiber material contains at least 80 wt. % of particles which can pass through sieve No. 80 and the added amount is within the range of from 10 wt. % to 80 wt. %, based on the total weight of the amino resin composition.
23. (Original) The amino resin composition for cleaning molds according to claims 14, wherein curing time of the amino resin composition for cleaning molds is in the range of 450 to 750 seconds, measured by using JSR type of curing meter.
24. (Previously amended) The amino resin composition for cleaning molds according to claim 14, which is made into a tablet form.
25. (Previously amended) The amino resin composition for cleaning molds according to claim 14, which is made into a sheet form.
26. (Previously amended) The amino resin composition for cleaning molds according to claim 14, which is made into a powder form.